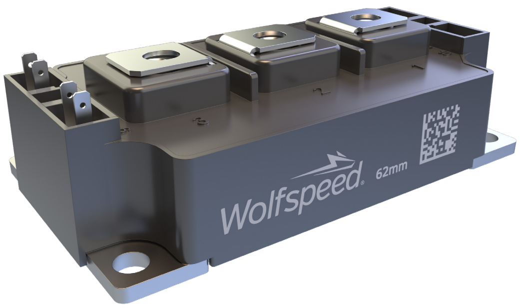
HAS310M17BM3

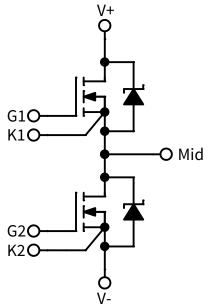
1700 V, 310 A, Silicon Carbide, Half-Bridge Module

V_{DS}	**1700 V**
I_{DS}	**310 A**

Technical Features

- Industry Standard 62 mm Footprint
- High Humidity Operation THB-80 (HV-H3TRB)
- Ultra Low Loss, High-Frequency Operation
- Zero Reverse Recovery from Diodes
- Zero Turn-off Tail Current from MOSFET
- Normally-off, Fail-safe Device Operation
- Copper Baseplate and Aluminum Nitride Insulator





Applications

- Induction Heating
- Motor Drives
- Renewables
- Railway Auxiliary & Traction
- EV Fast Charging
- UPS and SMPS

System Benefits

- 62 mm Form Factor Enables System Retrofit
- Increased System Efficiency, due to Low Switching & Conduction Losses of SiC

Key Parameters

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Drain-Source Voltage	V_{DS}			1700	V	T_C = 25 °C	
Gate-Source Voltage, Maximum Value	$V_{GS(max)}$	-8		+19		Transient	Note 1 Fig. 33
Gate-Source Voltage, Recommended	$V_{GS(op)}$		-4/+15			Static	
DC Continuous Drain Current	I_D		399		A	V_{GS} = 15 V, T_C = 25 °C, T_{VJ} ≤ 175 °C	Notes 2, 3 Fig. 21
			307			V_{GS} = 15 V, T_C = 90 °C, T_{VJ} ≤ 175 °C	
DC Source-Drain Current (Schottky Diode)	$I_{SD(SD)}$		482			V_{GS} =-4 V, T_C = 25 °C, T_{VJ} ≤ 175 °C	
Pulsed Drain-Source Current	I_{DM}		620			t_{Pmax} limited by T_{VJmax} V_{GS} = 15 V, T_C = 25 °C	
Power Dissipation	P_D		1630		W	T_C = 25 °C, T_{VJ} ≤ 175 °C	Note 4 Fig. 21
Virtual Junction Temperature	$T_{VJ(op)}$	-40		150	°C	Operation	
				175		Intermittent with Reduced Life	

Note (1): Recommended turn-on gate voltage is 15 V with ±5 % regulation tolerance
Note (2): Current limit calculated by $I_{D(max)} = \sqrt{(P_D/R_{DS(typ)}(T_{VJ(max)}, I_{D(max)}))}$
Note (3): Verified by design
Note (4): $P_D = (T_{VJ} - T_C)/R_{TH(JC,typ)}$

MOSFET Characteristics (Per Position) (T_{VJ} = 25 °C Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1700			V	V_{GS} = 0 V, T_{VJ} = -40 °C	
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.5	3.6	V	$V_{DS} = V_{GS}$, I_D = 102 mA	
			2.0			$V_{DS} = V_{GS}$, I_D = 102 mA, T_{VJ} = 175 °C	
Zero Gate Voltage Drain Current	I_{DSS}		26.4	2560	µA	V_{GS} = 0 V, V_{DS} = 1700 V	
Gate-Source Leakage Current	I_{GSS}		4	1000	nA	V_{GS} = 15 V, V_{DS} = 0 V	
Drain-Source On-State Resistance (Devices Only)	$R_{DS(on)}$		4.29	5.80	mΩ	V_{GS} = 15 V, I_D = 310 A	Fig. 2 Fig. 3
			8.42			V_{GS} = 15 V, I_D = 310 A, T_{VJ} = 150 °C	
Transconductance	g_{fs}		290		S	V_{DS} = 20 V, I_D = 310 A	Fig. 4
			284			V_{DS} = 20 V, I_D = 310 A, T_{VJ} = 150 °C	
Turn-On Switching Energy, T_{VJ} = 25 °C T_{VJ} = 125 °C T_{VJ} = 150 °C	E_{On}		4.4 4.1 4.0		mJ	V_{DD} = 900 V, I_D = 310 A, V_{GS} = -4 V/15 V, $R_{G(OFF)}$ = 1.0 Ω, $R_{G(ON)}$ = 1.0 Ω, L = 13.6 µH	Fig. 11 Fig. 13
Turn-Off Switching Energy, T_{VJ} = 25 °C T_{VJ} = 125 °C T_{VJ} = 150 °C	E_{Off}		7.2 7.4 7.4				
Internal Gate Resistance	$R_{G(int)}$		1.85		Ω	f = 100 kHz, V_{AC} = 25 mV	
Input Capacitance	C_{iss}		31.5		nF	V_{GS} = 0 V, V_{DS} = 1000 V, V_{AC} = 25 mV, f = 100 kHz	Fig. 9
Output Capacitance	C_{oss}		1.8				
Reverse Transfer Capacitance	C_{rss}		45		pF		
Gate to Source Charge	Q_{GS}		320		nC	V_{DS} = 1200 V, V_{GS} = -4 V/15 V, I_D = 310 A, Per IEC60747-8-4 pg 21	
Gate to Drain Charge	Q_{GD}		280				
Total Gate Charge	Q_G		996				
FET Thermal Resistance, Junction to Case	$R_{th\ JC}$		0.092		°C/W		Fig. 17

Diode Characteristics (Per Position) (T_{VJ} = 25 °C Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Diode Forward Voltage	V_F		1.78		V	V_{GS} = -4 V, I_F = 310 A, T_{VJ} = 25 °C	Fig. 7
			2.50			V_{GS} = -4 V, I_F = 310 A, T_{VJ} = 150 °C	
Reverse Recovery Time	t_{rr}		27		ns	V_{GS} = -4 V, I_{SD} = 310 A, V_R = 900 V di/dt = 26.5 A/ns, T_{VJ} = 150 °C	Fig. 32
Reverse Recovery Charge	Q_{rr}		4.5		µC		
Peak Reverse Recovery Current	I_{rrm}		281		A		
Reverse Recovery Energy, T_{VJ} = 25 °C T_{VJ} = 125 °C T_{VJ} = 150 °C	E_{rr}		3.5 3.8 3.9		mJ	V_{DS} = 900 V, I_D = 310 A, V_{GS} = -4 V/15 V, $R_{G(ext)}$ = 1.0 Ω, L = 13.6 µH	Fig. 14 Note 5
Diode Thermal Resistance, JCT. to Case	$R_{th\ JC}$		0.086		°C/W		Fig. 18

Note (5): SiC Schottky diodes do not have reverse recovery energy but still contribute capacitive energy

Module Physical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Package Resistance, M1 (High-Side)	$R_{3\text{-}1}$		1.31		mΩ	T_C = 25 °C, I_{SD} = 310 A, Note 6
			1.84			T_C = 125 °C, I_{SD} = 310 A, Note 6
Package Resistance, M2 (Low-Side)	$R_{1\text{-}2}$		1.26			T_C = 25 °C, I_{SD} = 310 A, Note 6
			1.77			T_C = 125 °C, I_{SD} = 310 A, Note 6
Stray Inductance	L_{Stray}		11.1		nH	Between DC- and DC+, f = 10 MHz
Case Temperature	T_C	-40		125	°C	
Mounting Torque	M_S	4	5	5.5	N-m	Baseplate, M6-1.0 Bolts
		4	5	5.5		Power Terminals, M6-1.0 Bolts
Weight	W		300		g	
Case Isolation Voltage	V_{isol}	5			kV	AC, 50 Hz, 1 minute
Comparative Tracking Index	CTI	600				Note 4
Clearance Distance		9			mm	Terminal to Terminal
		30				Terminal to Baseplate
Creepage Distance		30				Terminal to Terminal
		40				Terminal to Baseplate

Note (6): Total Effective Resistance (Per Switch Position) = MOSFET $R_{DS(on)}$ + Switch Position Package Resistance

Typical Performance

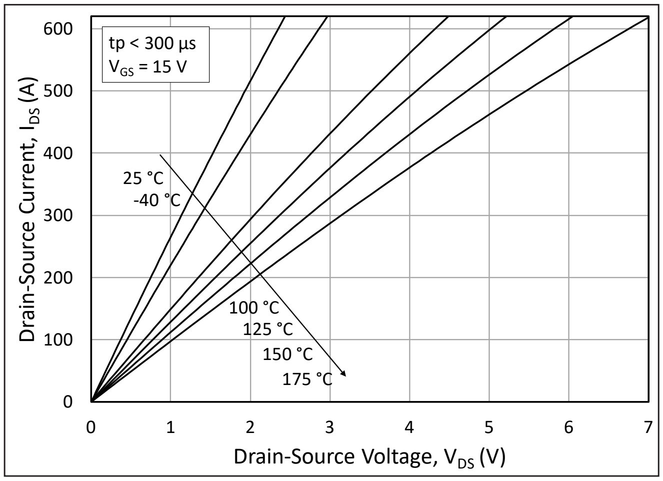


Figure 1. Output Characteristics for Various Junction Temperatures

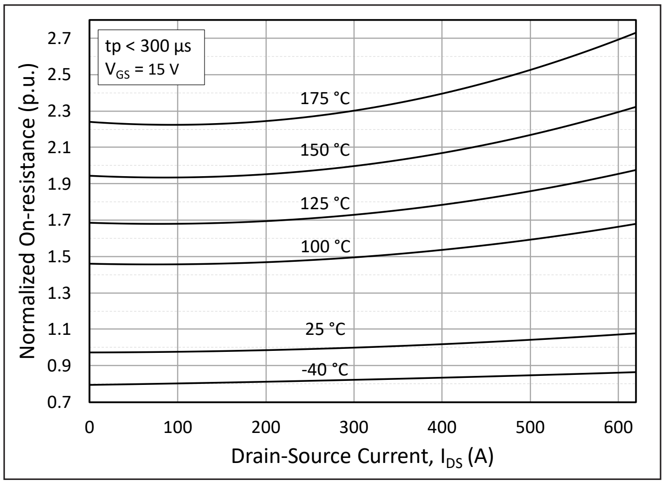


Figure 2. Normalized On-State Resistance vs. Drain Current for Various Junction Temperatures

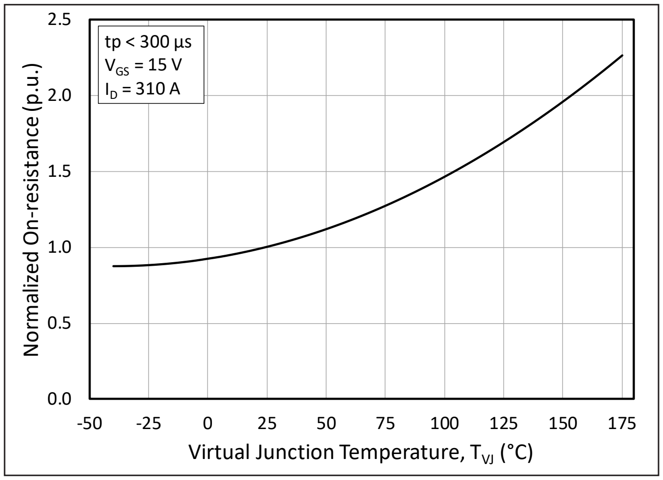


Figure 3. Normalized On-State Resistance vs. Junction Temperature

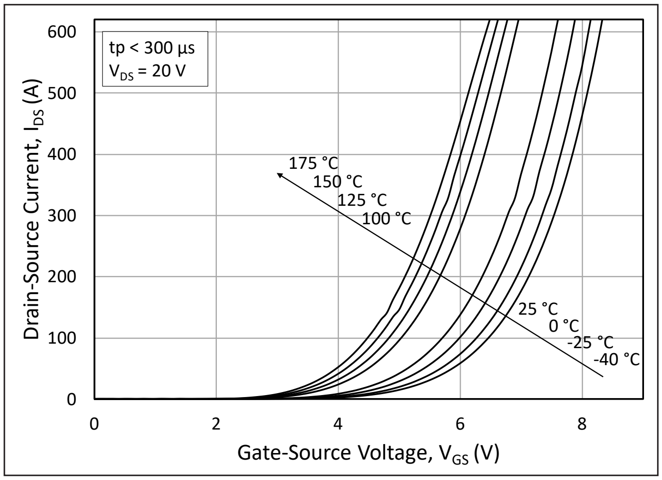


Figure 4. Transfer Characteristic for Various Junction Temperatures

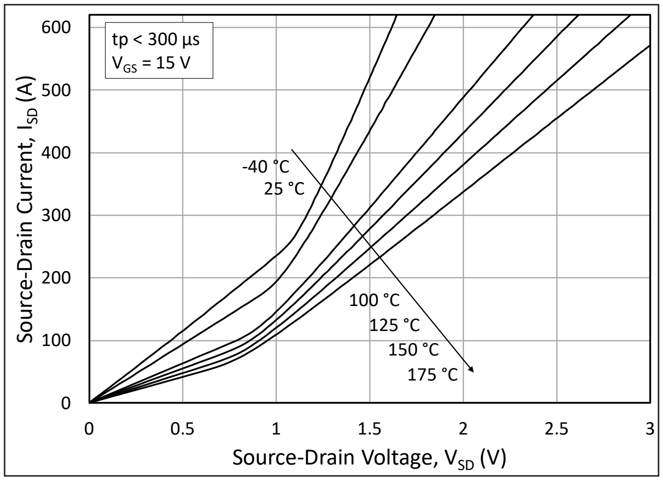


Figure 5. 3rd Quadrant Characteristic vs. Junction Temperatures at V_{GS} = 15 V

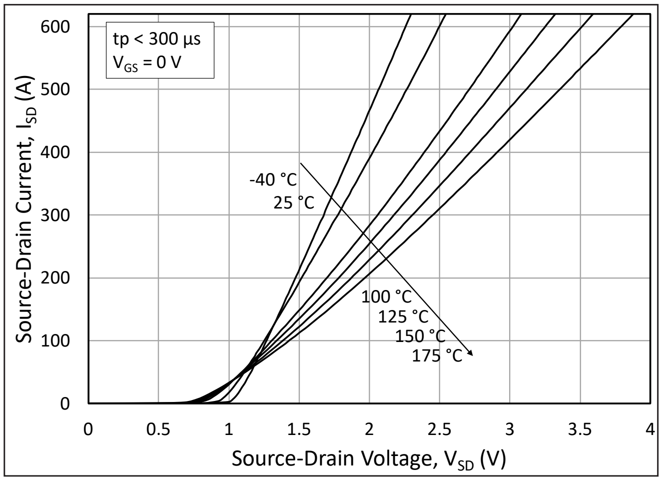


Figure 6. 3rd Quadrant Characteristic vs. Junction Temperatures at V_{GS} = 0 V (Diode)

Typical Performance

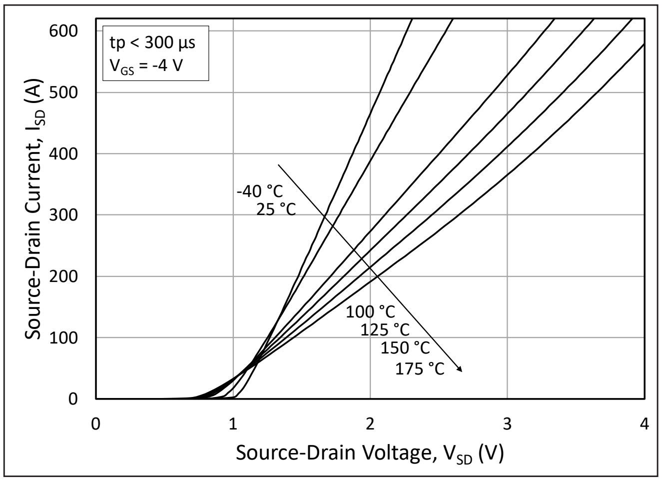


Figure 7. 3rd Quadrant Characteristic vs. Junction Temperatures at V_{GS} = -4 V (Diode)

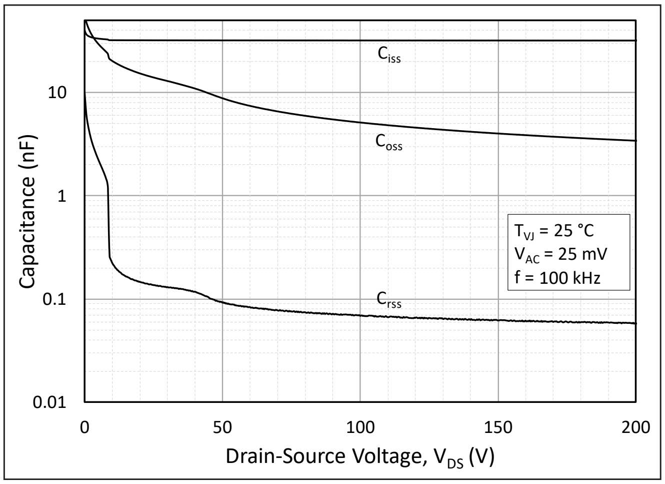


Figure 8. Typical Capacitances vs. Drain to Source Voltage (0 - 200 V)

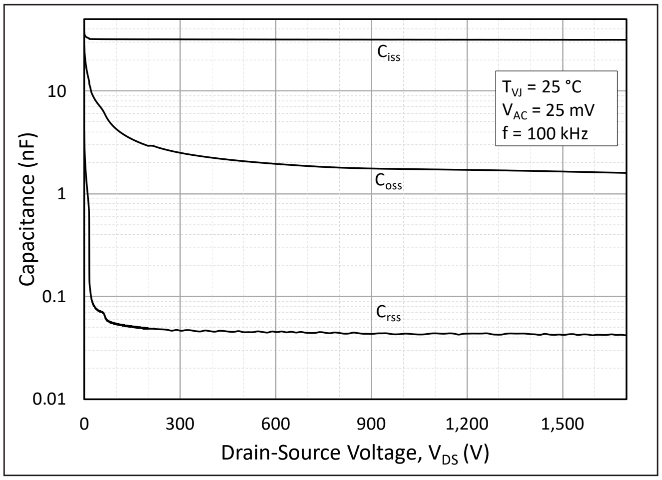


Figure 9. Typical Capacitances vs. Drain to Source Voltage (0 - 1700 V)

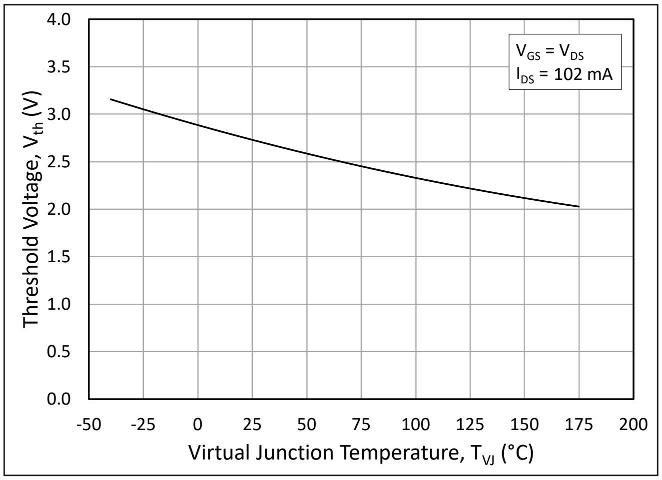


Figure 10. Threshold Voltage vs. Junction Temperature

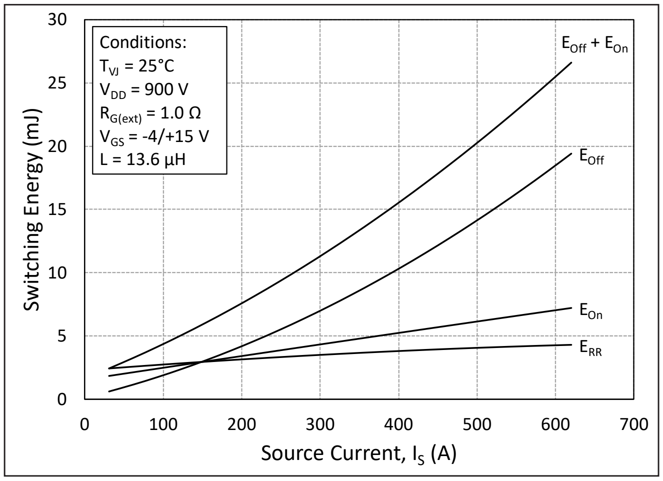


Figure 11. Switching Energy vs. Drain Current (V_{DD} = 900 V)

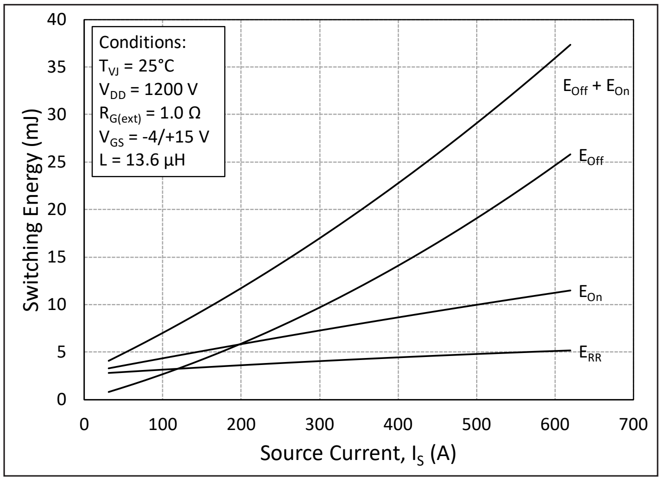


Figure 12. Switching Energy vs. Drain Current (V_{DD} = 1200 V)

Typical Performance

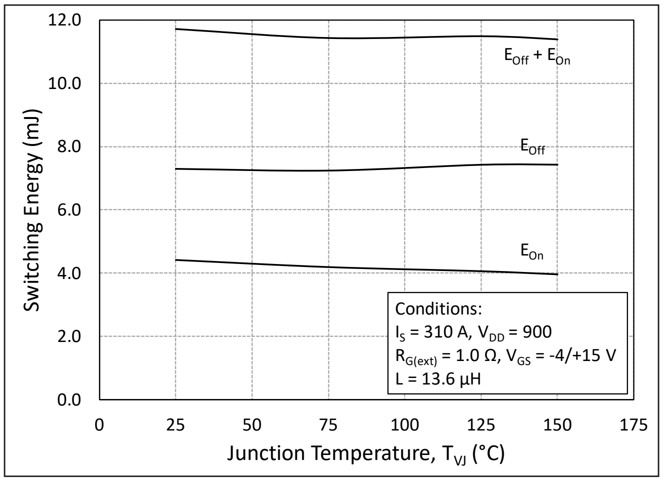


Figure 13. MOSFET Switching Energy vs. Junction Temperature

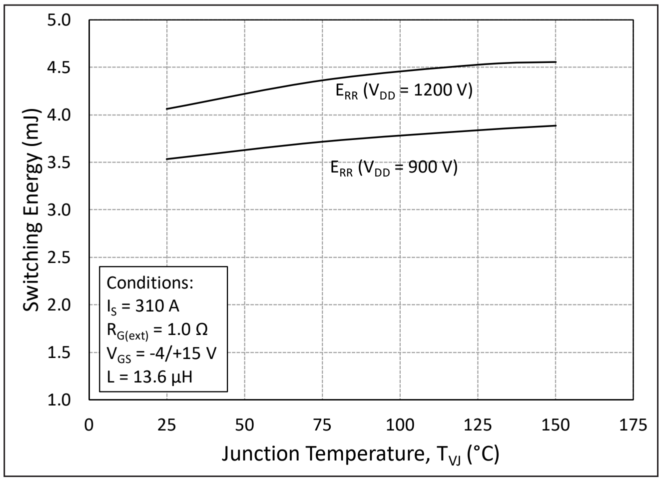


Figure 14. Reverse Recovery Energy vs. Junction Temperature

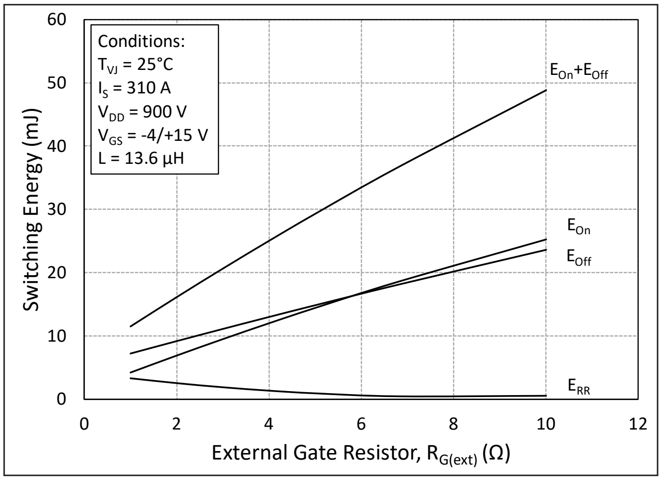


Figure 15. MOSFET Switching Energy vs. External Gate Resistance

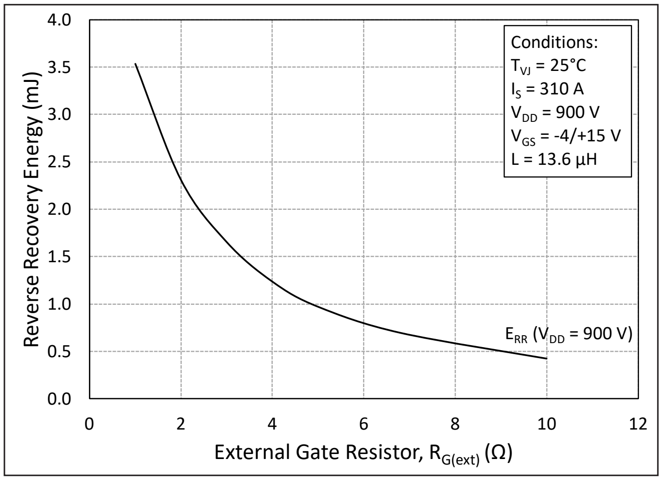


Figure 16. Reverse Recovery Energy vs. External Gate Resistance

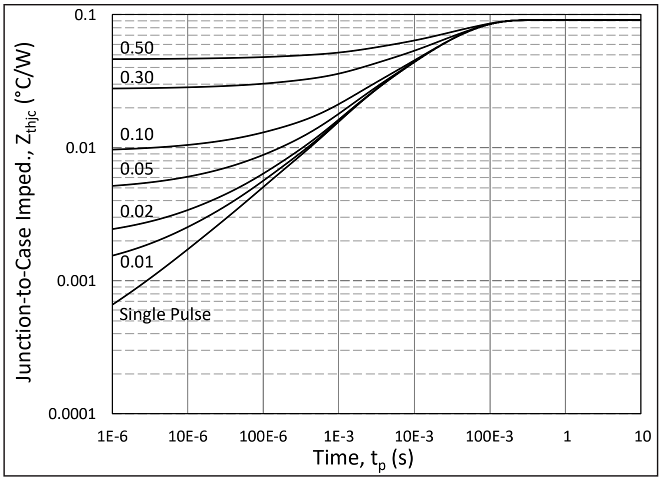


Figure 17. MOSFET Junction to Case Transient Thermal Impedance, $Z_{th,jc}$ (°C/W)

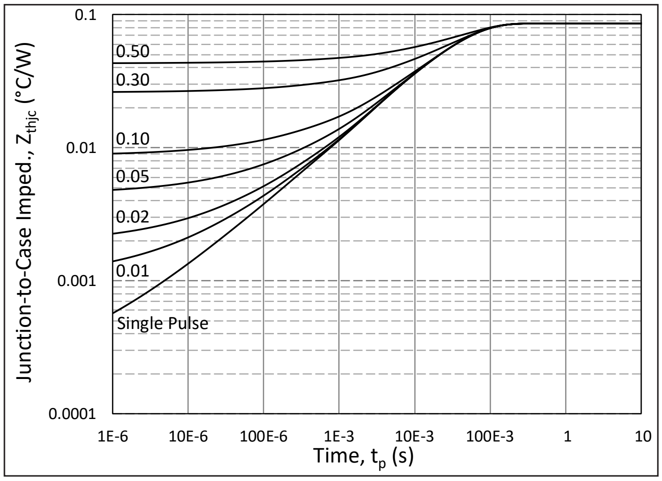


Figure 18. Diode Junction to Case Transient Thermal Impedance, $Z_{th,jc}$ (°C/W)

Typical Performance

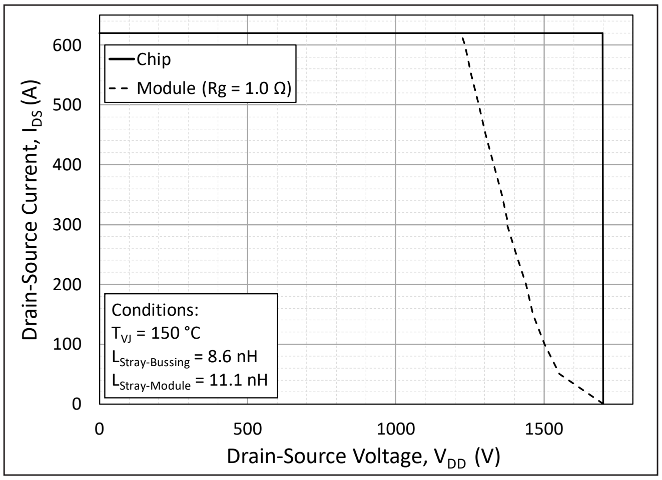


Figure 19. Switching Safe Operating Area

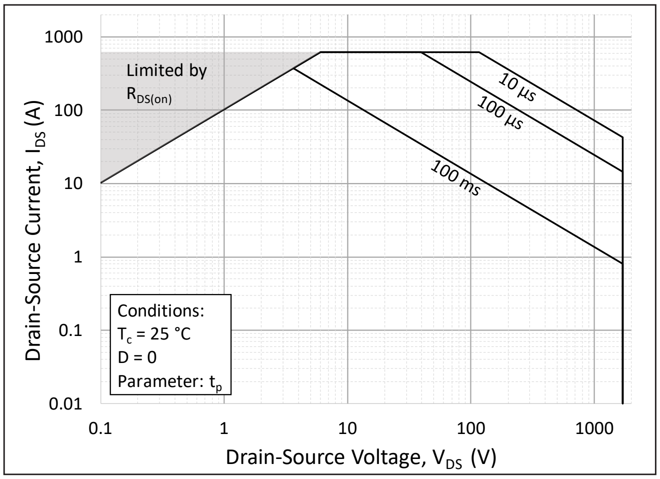


Figure 20. Forward Bias Safe Operating Area (FBSOA)

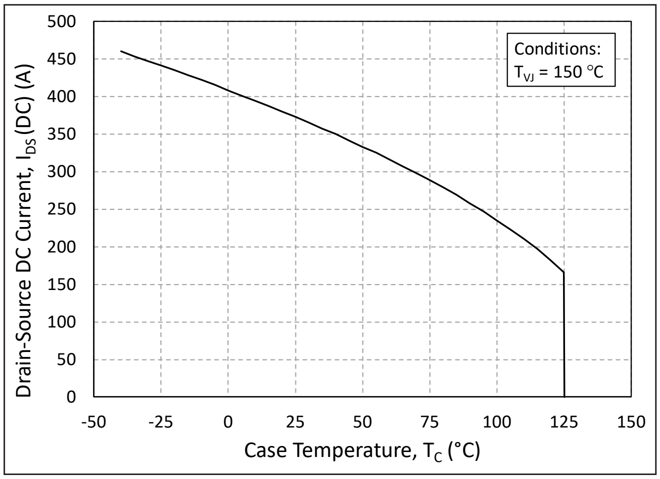


Figure 21. Continuous Drain Current Derating vs. Case Temperature

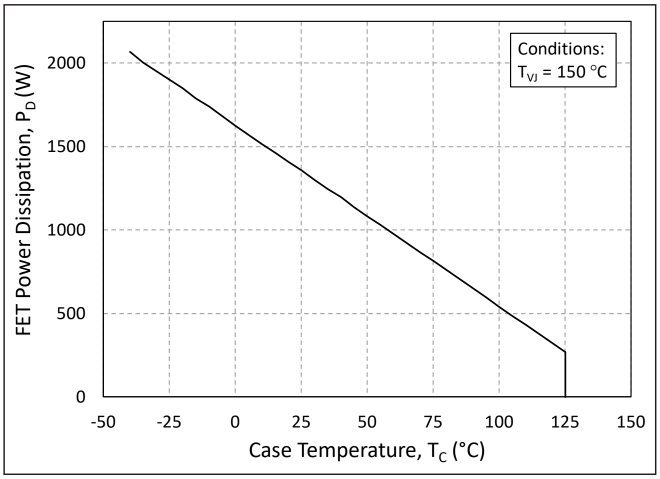


Figure 22. Maximum Power Dissipation Derating vs. Case Temperature

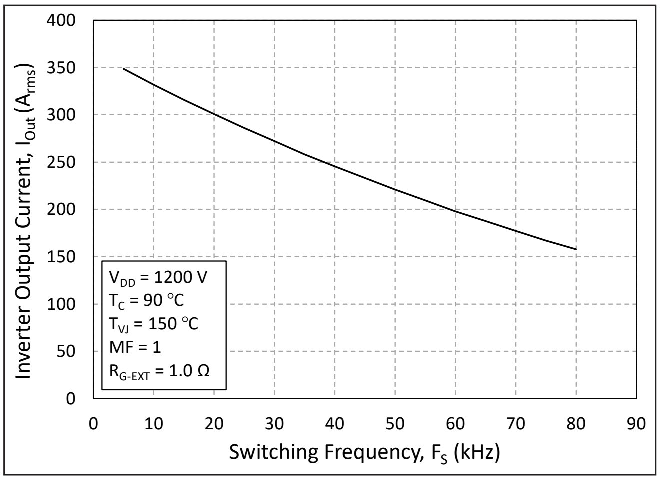


Figure 23. Typical Output Current Capability vs. Switching Frequency (Inverter Application)

Timing Characteristics

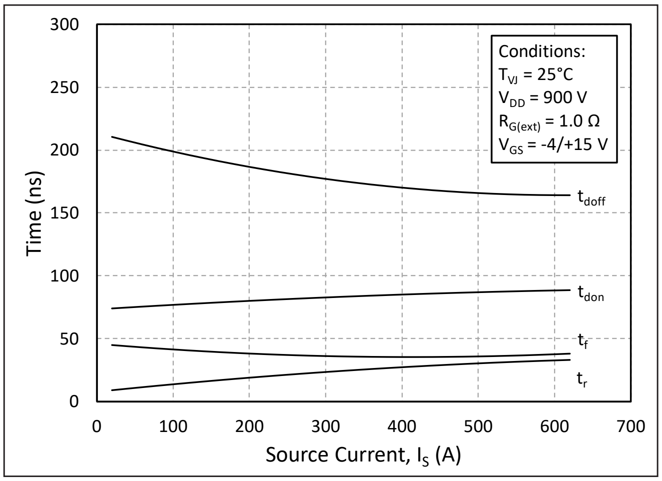


Figure 24. Timing vs. Source Current

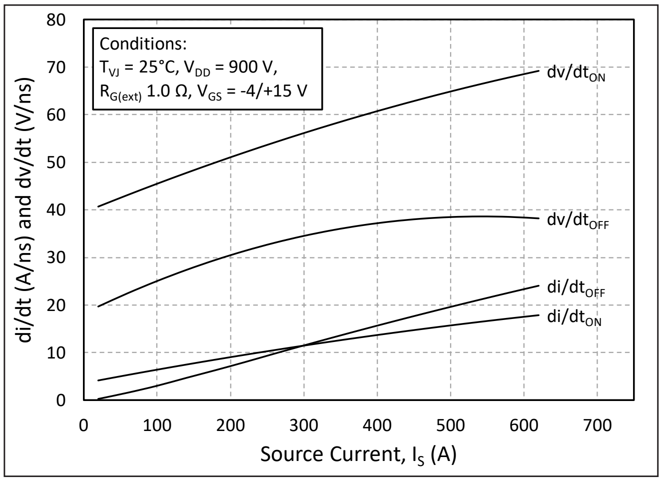


Figure 25. dv/dt and di/dt vs. Source Current

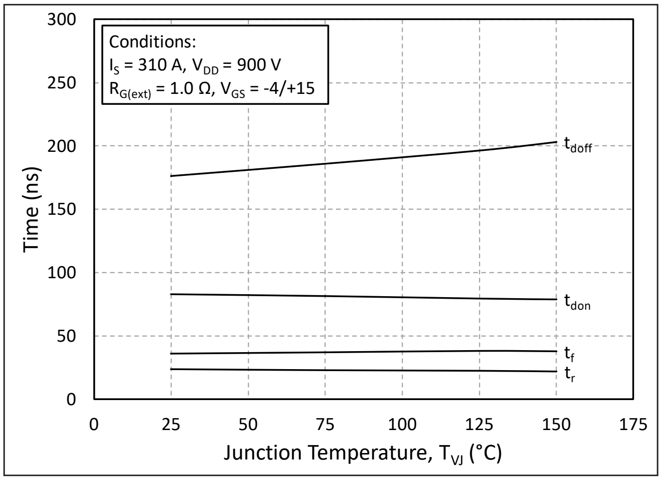


Figure 26. Timing vs. Junction Temperature

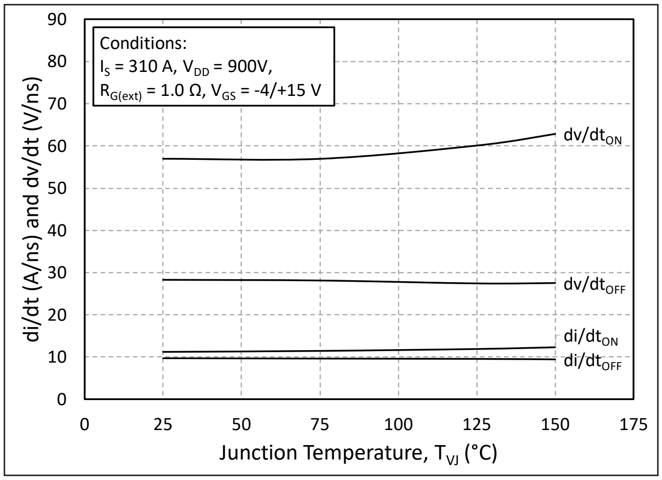


Figure 27. dv/dt and di/dt vs. Junction Temperature

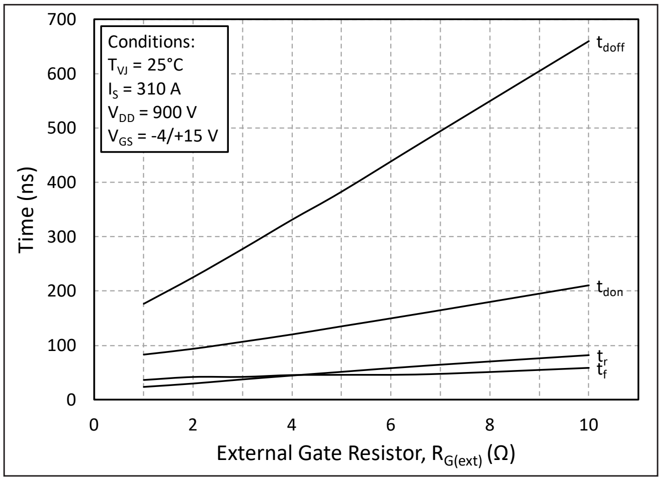


Figure 28. Timing vs. External Gate Resistance

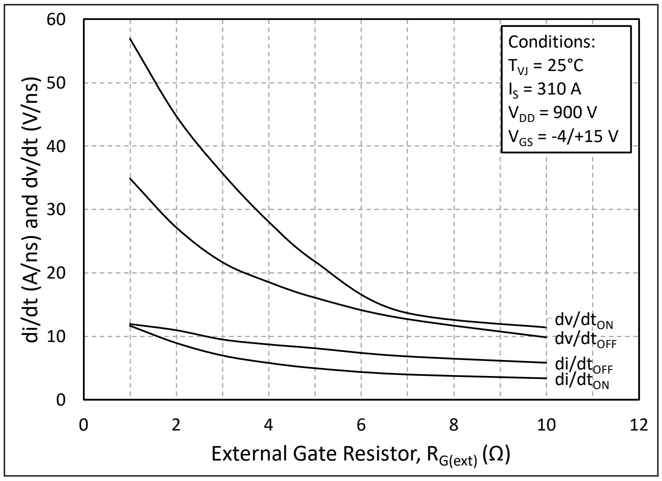


Figure 29. dv/dt and di/dt vs. External Gate Resistance

Definitions

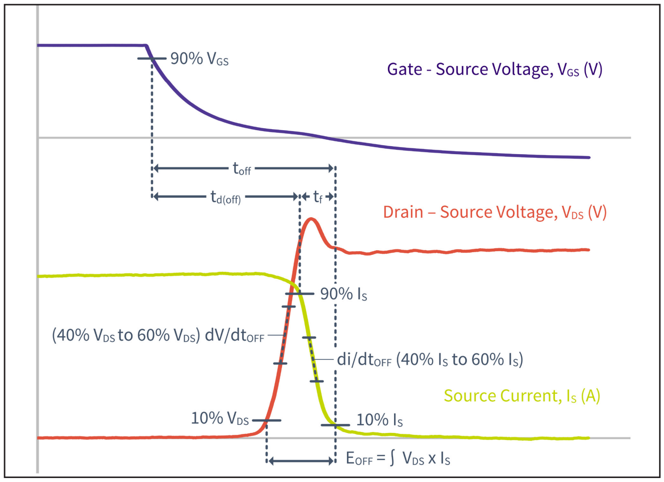


Figure 30. Turn-Off Transient Definitions

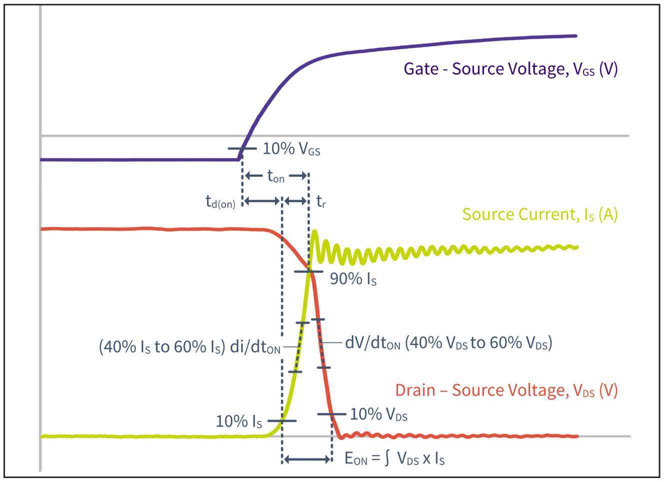


Figure 31. Turn-On Transient Definitions

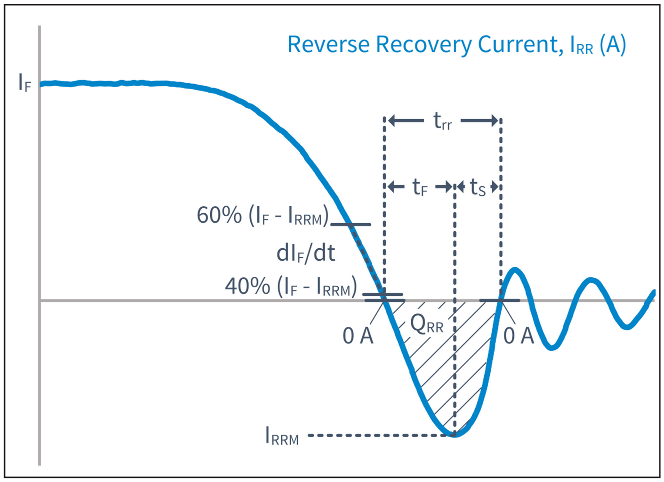


Figure 32. Reverse Recovery Definitions

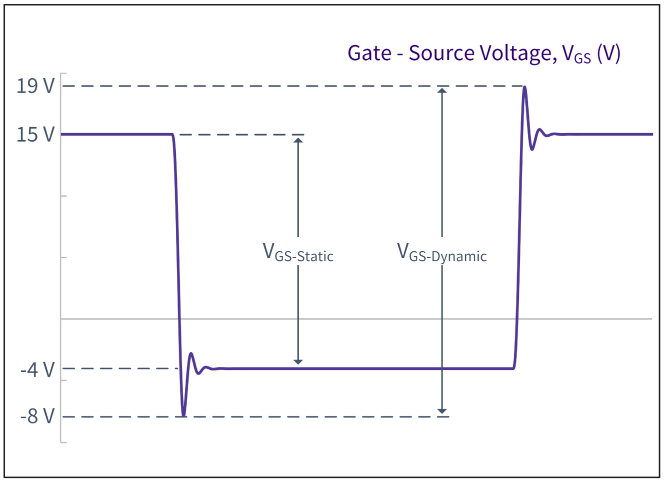
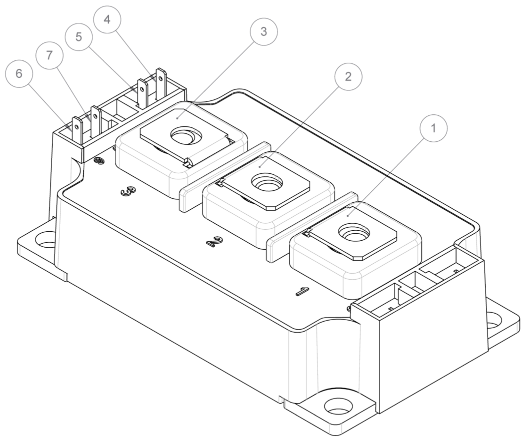
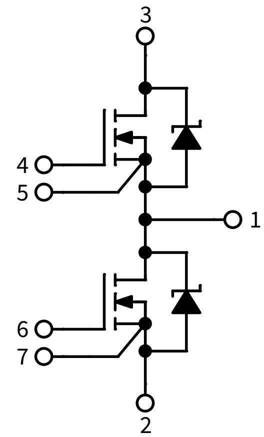


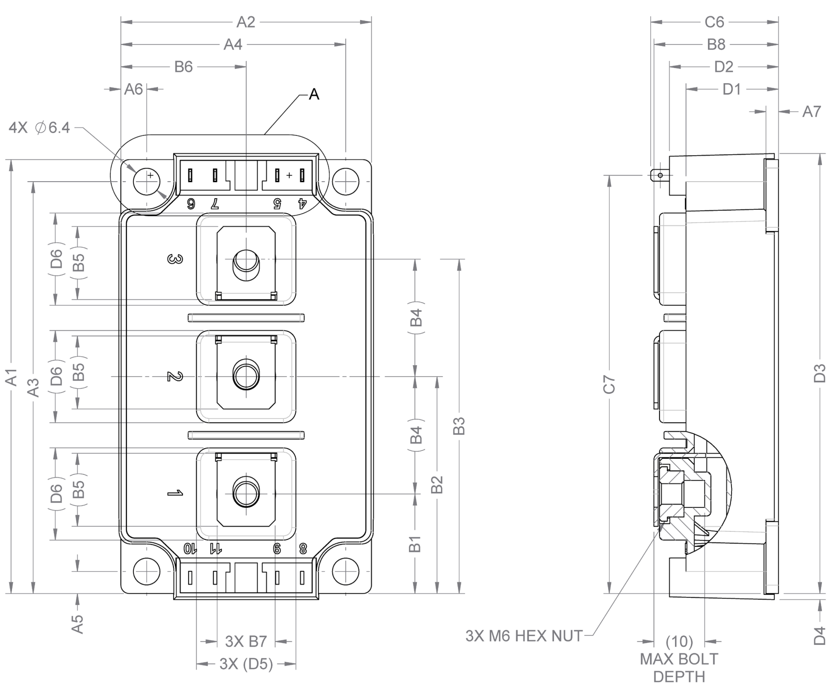
Figure 33. V_{GS} Transient Definitions

Schematic and Pin Out

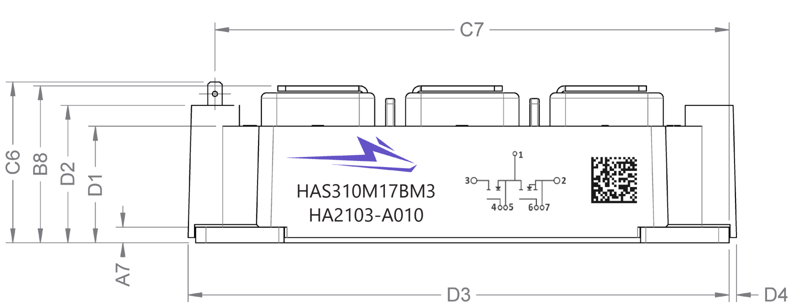


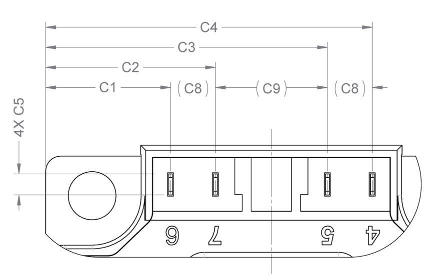


Package Dimension (mm)



DIMENSION TABLE		
SYMBOL	DIMENSION	TOLERANCE
A1	103.5	±0.30
A2	60.44	±0.30
A3	98.25	±0.30
A4	54.22	±0.30
A5	5.25	±0.30
A6	6.22	±0.30
A7	3	±0.30
B1	23.75	±0.40
B2	51.75	±0.40
B3	79.75	±0.40
B4	(28)	REF.
B5	(17.43)	REF.
B6	30.23	±0.40
B7	(14)	REF.
B8	30.03	±0.40
C1	16.73	±0.40
C2	22.73	±0.40
C3	37.73	±0.40
C4	43.73	±0.40
C5	2.8	±0.40
C6	30.8	±0.50
C7	99.75	±0.40
C8	(6)	REF.
C9	(15)	REF.
D1	22.3	±0.30
D2	26.3	±0.30
D3	104.95	±0.30
D4	1.45	±0.40
D5	(24)	REF.
D6	(22)	REF.





DETAIL A
SCALE 3 : 1

Supporting Links & Tools

Evaluation Tools & Support

- PLECS Models
- LTSpice Models
- KIT-CRD-CIL17N-BM: Dynamic Performance Evaluation Board for the BM2 and BM3 Module
- SpeedFit 2.0 Design Simulator™
- Technical Support Forum

Dual-Channel Gate Driver Board

- CGD1700HB2P-BM3: Dual Channel Isolated Half Bridge Gate Driver Board
- CGD12HB00D: Differential Transceiver Daughter Board Companion Tool for Differential Gate Drivers

Application Notes

- CPWR-AN35: 62 mm Module Thermal Interface Material Application Note

Notes & Disclaimer

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The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Documentation sections of www.wolfspeed.com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact your Wolfspeed representative to ensure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

Contact info:

4600 Silicon Drive
Durham, NC 27703 USA
Tel: +1.919.313.5300
www.wolfspeed.com/power

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